

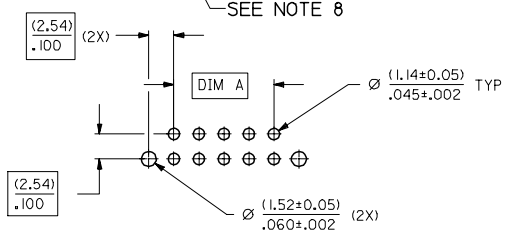
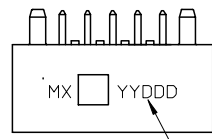
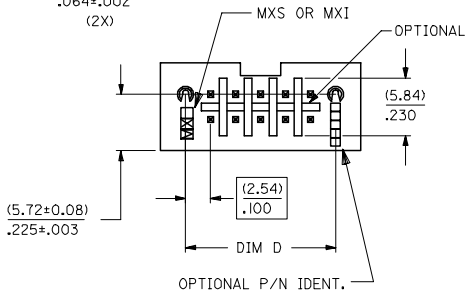
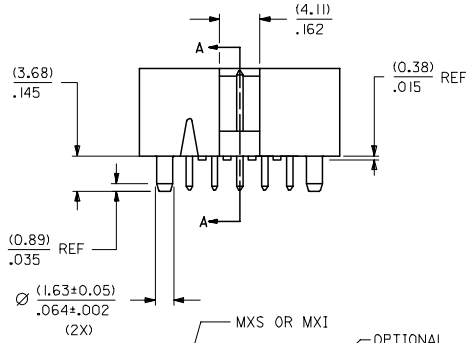
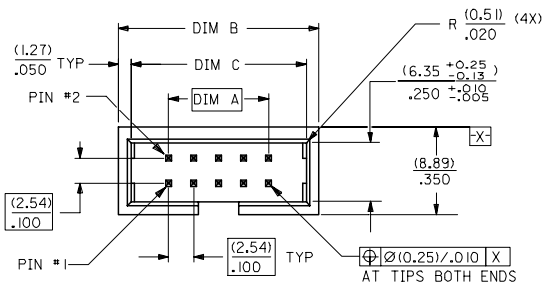
10 9 8 7 6 5 4 3 2 1

**PART NUMBER LEGEND**

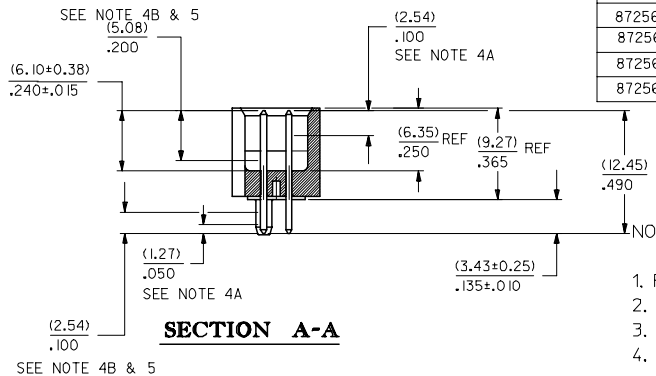
87256 - \* \* 11

CKT SIZES

ASSEMBLY P/N	CKT SIZE	DIM A	DIM B	DIM C	DIM D
87256-0411	04	(2.54)/.100	(12.70)/.500	(10.16)/.400	(7.62)/.300
87256-0611	06	(5.08)/.200	(15.24)/.600	(12.70)/.500	(10.16)/.400
87256-0811	08	(7.62)/.300	(17.78)/.700	(15.24)/.600	(12.70)/.500
87256-1011	10	(10.16)/.400	(20.32)/.800	(17.78)/.700	(15.24)/.600
87256-1211	12	(12.70)/.500	(22.86)/.900	(20.32)/.800	(17.78)/.700
87256-1411	14	(15.24)/.600	(25.40)/1.000	(22.86)/.900	(20.32)/.800
87256-1611	16	(17.78)/.700	(27.94)/1.100	(25.40)/1.000	(22.86)/.900
87256-1811	18	(20.32)/.800	(30.48)/1.200	(27.94)/1.100	(25.40)/1.000
87256-2011	20	(22.86)/.900	(33.02)/1.300	(30.48)/1.200	(27.94)/1.100
87256-2411	24	(27.94)/1.100	(38.10)/1.500	(35.56)/1.400	(33.02)/1.300
87256-2611	26	(30.48)/1.200	(40.64)/1.600	(38.10)/1.500	(35.56)/1.400
87256-3011	30	(35.56)/1.400	(45.72)/1.800	(43.18)/1.700	(40.64)/1.600
87256-3411	34	(40.64)/1.600	(50.80)/2.000	(48.26)/1.900	(45.72)/1.800
87256-4011	40	(48.26)/1.900	(58.42)/2.300	(55.88)/2.200	(53.34)/2.100
87256-4411	44	(53.34)/2.100	(63.50)/2.500	(60.96)/2.400	(58.42)/2.300
87256-5011	50	(60.96)/2.400	(71.12)/2.800	(68.58)/2.700	(66.04)/2.600
87256-5611	56	(68.58)/2.700	(78.74)/3.100	(76.20)/3.000	(73.66)/2.900
87256-6011	60	(73.66)/2.900	(83.82)/3.300	(81.28)/3.200	(78.74)/3.100
87256-6411	64	(78.74)/3.100	(88.90)/3.500	(86.36)/3.400	(83.82)/3.300
87256-7211	72	(88.90)/3.500	(99.06)/3.900	(96.52)/3.800	(93.98)/3.700



**RECOMMENDED PCB PATTERN**



**SECTION A-A**

- NOTES:
- PIN PUSHOUT FORCE (0.9072 KG)/2 LBS MIN.
  - PRODUCT SPECIFICATION #70246 APPLIES.
  - WAFER TO BE FLAT WITHIN (0.03MM/CM)/.003IN/IN.
  - DIMENSIONS FOR PLATING LOCATIONS : A - MEASURE POINT FOR THICKNESS.  
B - MINIMUM COVERAGE.
  - GOLD END OF PIN UNLESS OVERALL PLATED.
  - FINISH : (PER ES-88)  
0.13um/5u\* MIN GOLD FLASH OVER 1.02um/100u\* MIN.PD/NI  
IN SELECTED AREA AND 2.5um/100u\* MIN.TIN/LEAD IN SELECTED AREA OVER 1.27um/50u\* MIN NICKEL OVERALL
  - FOR ILLUSTRATION PURPOSE A 10 CKT IS SHOWN.
  - OPTIONAL LOCATION FOR MANUFACTURER/YEAR/DAY MARKING IF REQUIRED BY CUSTOMER.

(MM)  
INCH

<b>HSG LASER MARKING</b> EC NO: S2005-0536 DRAWN:LOIAO 2005/01/26 CHKD:PTLIM 2005/01/26 APPR:SCLOW 2005/01/27	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± .008	2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	DRAWN BY DATE OLKHO 1990/08/03		TITLE C-GRID, SHROUDED WAFER SLOTTED, WITH IN-LINE POLARIZATION PEGS		
		ANGULAR ± 3 °				CHECKED BY DATE MLA1 1990/11/28		MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				APPROVED BY DATE RWONG 1990/11/28		DOCUMENT NO. SDA-87256-**11		SHEET NO. 1 OF 1

9 8 7 6 5 4 3 2 1